



PATENT

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicants: Kim et al.

Serial No.: 10/032,687

Filed: December 28, 2001

For: METHOD OF FORMING
WIRING IN SEMICONDUCTOR
DEVICES

Group Art Unit: 2822

Examinar: Maria F. Guerrero

I hereby certify that this paper is being deposited with the United States Postal Service, first class postage prepaid, addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

January 30, 2004

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RESPONSE TO OFFICIAL ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This papers is in response to the official action of October 3, 2003. This response is timely-filed as it is accompanied by a petition for extension of time to file in the first month, and the requisite extension fee.

Claims 1-4 are pending in the application and have been rejected. Reconsideration is respectfully requested.

Claim Rejections – 35 U.S.C. §103

Claims 1-4 stand rejected under 35 U.S.C. §103(a) as being unpatentable over applicants' allegedly admitted prior art in view of Harakawa JP 07-183513 and Beinglass et al. U.S. Patent No. 5,932,286.

The present invention is intended to solve the problem that a lift or a crack is generated in an interface due to the difference in the stress between two types of nitride films,